

Technical Data Sheet

Schulamid 66 MK20 HI BLK968001

Polyamide 66

Product Description

20% mineral filled PA 66, impact modified

Processing Method	Injection Molding
Attribute	Impact Modified
Additive	Impact Modifier
Filler/Reinforcement	Mineral, 20%

Typical Properties	Nominal Value	Units	Test Method
Physical			
Density, (Method A)	1.28	g/cm ³	ISO 1183
Mechanical			
Tensile Strain at Break			
(Type 1A, 5 mm/min)	12	%	ISO 527-2
(Type 1A, 5 mm/min) - Conditioned	16	%	ISO 527-2
Tensile Stress at Break			
(Type 1A, 5 mm/min)	70.0	MPa	ISO 527-2
(Type 1A, 5 mm/min) - Conditioned	45.0	MPa	ISO 527-2
Tensile Modulus			
(1 mm/min, Type 1A)	3500	MPa	ISO 527-1
(1 mm/min, Type 1A) - Conditioned	2000	MPa	ISO 527-1
Impact			
Charpy Impact Strength - Notched			
(23 °C, Type 1, Edgewise, Notch A)	8.0	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A)	6.0	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise, Notch A) - Conditioned	14	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A) - Conditioned	5.0	kJ/m ²	ISO 179
Charpy Impact Strength - Unnotched			
(23 °C, Type 1, Edgewise)	130	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise)	120	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise) - Conditioned	No Break		ISO 179
(-30 °C, Type 1, Edgewise) - Conditioned	170	kJ/m ²	ISO 179
Hardness			
Ball Indentation Hardness, (H 358/30)	170	MPa	ISO 2039-1
Ball Pressure Test, (100 °C)	Pass		IEC 60695-10-2
Thermal			

Deflection Temperature Under Load Unannealed (0.45 MPa), (Flatwise)	170	°C	ISO 75-2/B
Deflection Temperature Under Load Unannealed (1.80 MPa), (Flatwise)	90.0	°C	ISO 75-2/A
Electrical			
Volume Resistivity	>1.0E+13	ohm*m	IEC 62631-3-1
- Conditioned	10000000000	ohm*m	IEC 62631-3-1
Comparative Tracking Index (CTI)	550	V	IEC 60112
Surface Resistivity	>1.0E+15	ohm	IEC 60093
Flammable			
Burning Rate			
(2.00 mm)	<100	mm/min	ISO 3795
(2.00 mm)	<100	mm/min	FMVSS 302
UL Information			
Flammability Classification, (3.2 mm)	HB		IEC 60695-11-10, -20

Injection Parameters		Nominal Value	Units
Drying Time		3.0 to 4.0	hr
Drying Temperature		80	°C
Suggested Max Moisture		0.040 to 0.10	%
Processing (Melt) Temp		280 to 300	°C
Mold Temperature		60 to 120	°C